


SUMITOMO BAKELITE
TECHNICAL REPORT

Liquid Epoxy Resin for Electronics

SUMIMAC®

One Component Liquid Epoxy Resin Composition

“SUMIMAC”[®] ECR-8000 Series

For Secondary Underfill

ECR-8002K

“SUMIMAC”[®] ECR-8002K is designed for secondary underfill and is suitable for CSP or BGA etc.

ECR-8002K is one component epoxy resin with low-temperature fast cure, has low CTE and good reworkability .

Properties

Items	Unit/Condition	ECR-8002K
Appearance	-	Black Liquid
Viscosity	Pa.s/25C	5
Gelation time	sec./150C	80
Standard curing condition	-	100Cx40min or 120Cx30min.


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Other Properties

Items	Unit/Condition	ECR-8002K
Flexural strength	MPa	110
Flexural Modulus	GPa	11
Tg (TMA method)	C	130
α_1/α_2 (TMA method)	ppm	20/68
Adhesion strength (Solder resist)	MPa/25C	8
Volume resistivity	$\Omega \cdot \text{cm}$	1.0E+16
Flow ability (CSP:10X10mm Gap0.4mm)	sec./ 60C	25

TMA:Thermal Mechanical Analysis
 α_1/α_2 =Thermal expansion(at25C/at150C)